

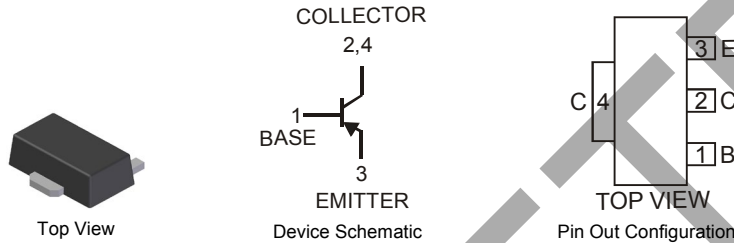
**LOW VCE(SAT) PNP SURFACE MOUNT TRANSISTOR**

**Features**

- Epitaxial Planar Die Construction
- Ideally Suited for Automated Assembly Processes
- Ideal for Medium Power Switching or Amplification Applications
- Complementary NPN Type (2DD2679) Available
- **Lead Free By Design/RoHS Compliant (Note 1)**
- **"Green" Device (Note 2)**

**Mechanical Data**

- Case: SOT89-3L
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminals: Finish — Matte Tin annealed over Copper leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208
- Marking Information: See Page 4
- Ordering Information: See Page 4
- Weight: 0.072 grams (approximate)



**Maximum Ratings** @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	-30	V
Collector-Emitter Voltage	V <sub>CEO</sub>	-30	V
Emitter-Base Voltage	V <sub>EBO</sub>	-6	V
Peak Pulse Current	I <sub>CM</sub>	-4	A
Continuous Collector Current	I <sub>C</sub>	-2	A

**Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 3) @ T <sub>A</sub> = 25°C	P <sub>D</sub>	0.9	W
Thermal Resistance, Junction to Ambient Air (Note 3) @ T <sub>A</sub> = 25°C	R <sub>θJA</sub>	139	°C/W
Power Dissipation (Note 4) @ T <sub>A</sub> = 25°C	P <sub>D</sub>	2	W
Thermal Resistance, Junction to Ambient Air (Note 4) @ T <sub>A</sub> = 25°C	R <sub>θJA</sub>	62.5	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

**Electrical Characteristics** @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Conditions
<b>OFF CHARACTERISTICS</b>						
Collector-Base Breakdown Voltage	V <sub>(BR)CBO</sub>	-30	—	—	V	I <sub>C</sub> = -10μA, I <sub>E</sub> = 0
Collector-Emitter Breakdown Voltage (Note 5)	V <sub>(BR)CEO</sub>	-30	—	—	V	I <sub>C</sub> = -1mA, I <sub>B</sub> = 0
Emitter-Base Breakdown Voltage	V <sub>(BR)EBO</sub>	-6	—	—	V	I <sub>E</sub> = -10μA, I <sub>C</sub> = 0
Collector Cut-Off Current	I <sub>CBO</sub>	—	—	-0.1	μA	V <sub>CB</sub> = -30V, I <sub>E</sub> = 0
Emitter Cut-Off Current	I <sub>EBO</sub>	—	—	-0.1	μA	V <sub>EB</sub> = -6V, I <sub>C</sub> = 0
<b>ON CHARACTERISTICS (Note 5)</b>						
Collector-Emitter Saturation Voltage	V <sub>CE(sat)</sub>	—	—	-370	mV	I <sub>C</sub> = -1.5A, I <sub>B</sub> = -75mA
DC Current Gain	h <sub>FE</sub>	270	—	680	—	V <sub>CE</sub> = -2V, I <sub>C</sub> = -200mA
<b>SMALL SIGNAL CHARACTERISTICS</b>						
Output Capacitance	C <sub>obo</sub>	—	16	—	pF	V <sub>CB</sub> = -10V, I <sub>E</sub> = 0, f = 1MHz
Current Gain-Bandwidth Product	f <sub>T</sub>	—	200	—	MHz	V <sub>CE</sub> = -2V, I <sub>C</sub> = -100mA, f = 100MHz

- Notes:
1. No purposefully added lead.
  2. Diodes Inc.'s "Green" policy can be found on our website at [http://www.diodes.com/products/lead\\_free/index.php](http://www.diodes.com/products/lead_free/index.php).
  3. Device mounted on FR-4 PCB with minimum recommended pad layout.
  4. Device mounted on FR-4 PCB with 1 inch<sup>2</sup> copper pad layout.
  5. Measured under pulsed conditions. Pulse width = 300μs. Duty cycle ≤2%.

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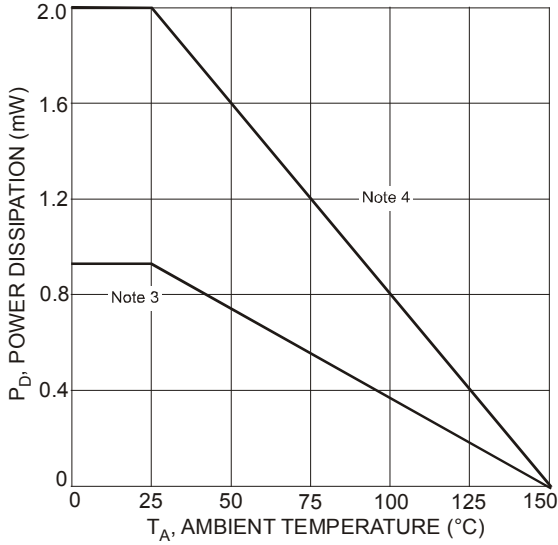


Fig. 1 Power Dissipation vs. Ambient Temperature

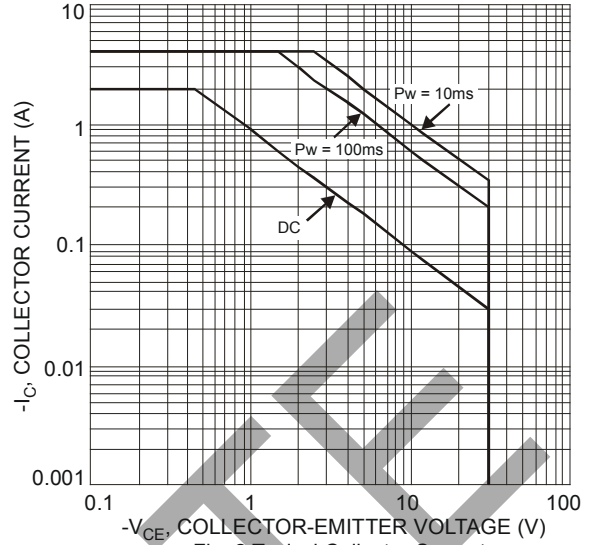


Fig. 2 Typical Collector Current vs. Collector-Emitter Voltage (Note 3)

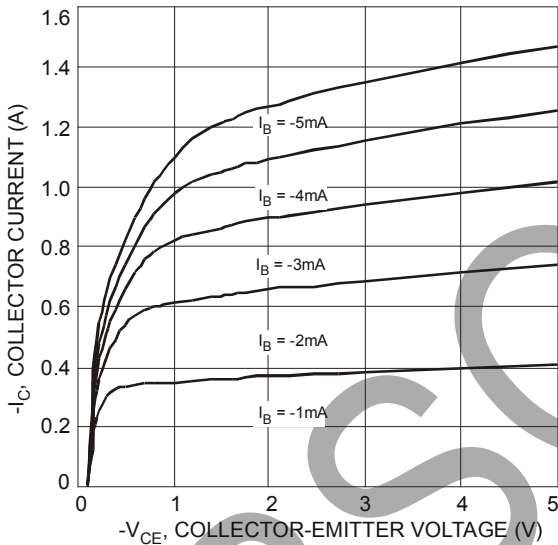


Fig. 3 Typical Collector Current vs. Collector-Emitter Voltage

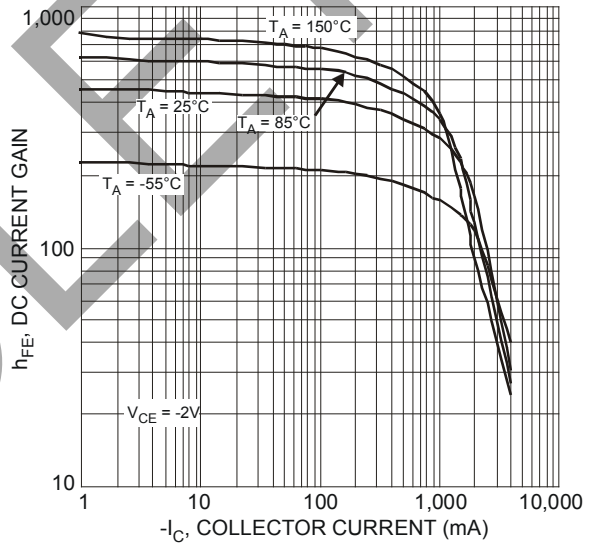


Fig. 4 Typical DC Current Gain vs. Collector Current

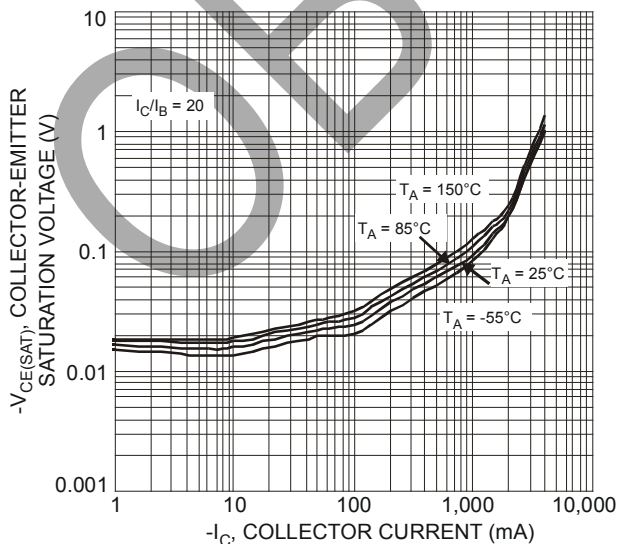


Fig. 5 Typical Collector-Emitter Saturation Voltage vs. Collector Current

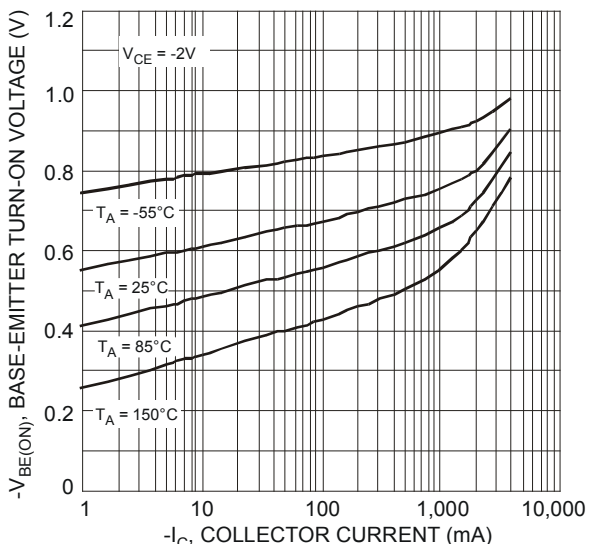


Fig. 6 Typical Base-Emitter Turn-On Voltage vs. Collector Current

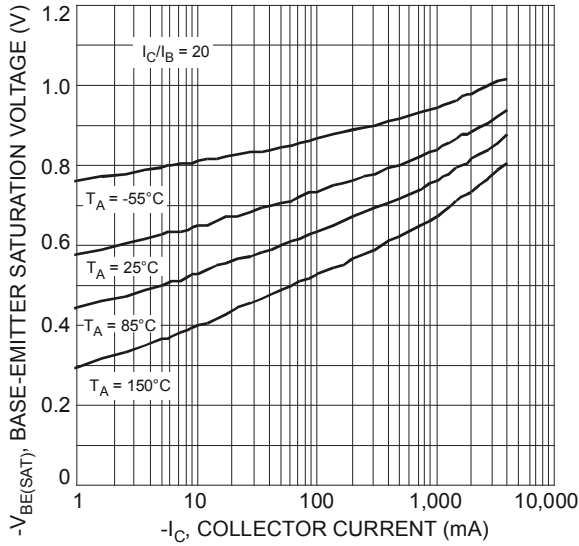


Fig. 7 Typical Base-Emitter Saturation Voltage vs. Collector Current

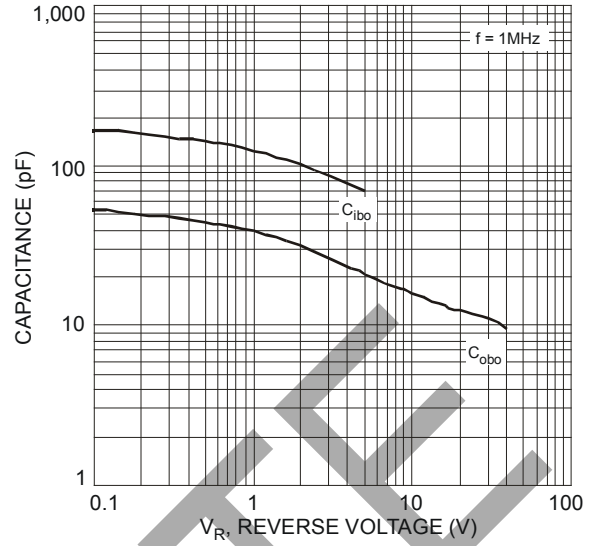


Fig. 8 Typical Capacitance Characteristics

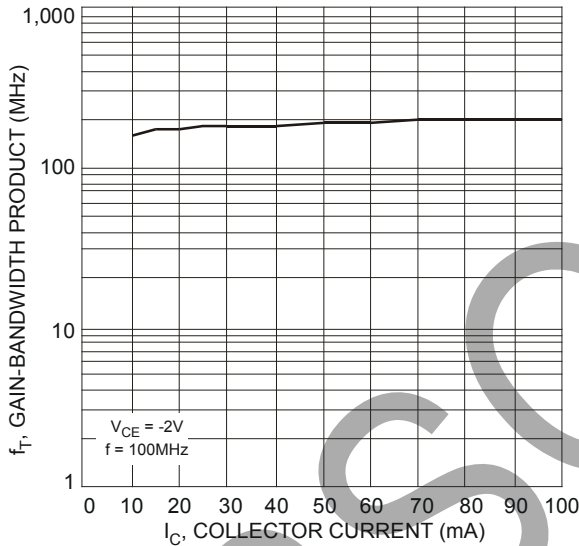


Fig. 9 Typical Gain-Bandwidth Product vs. Collector Current

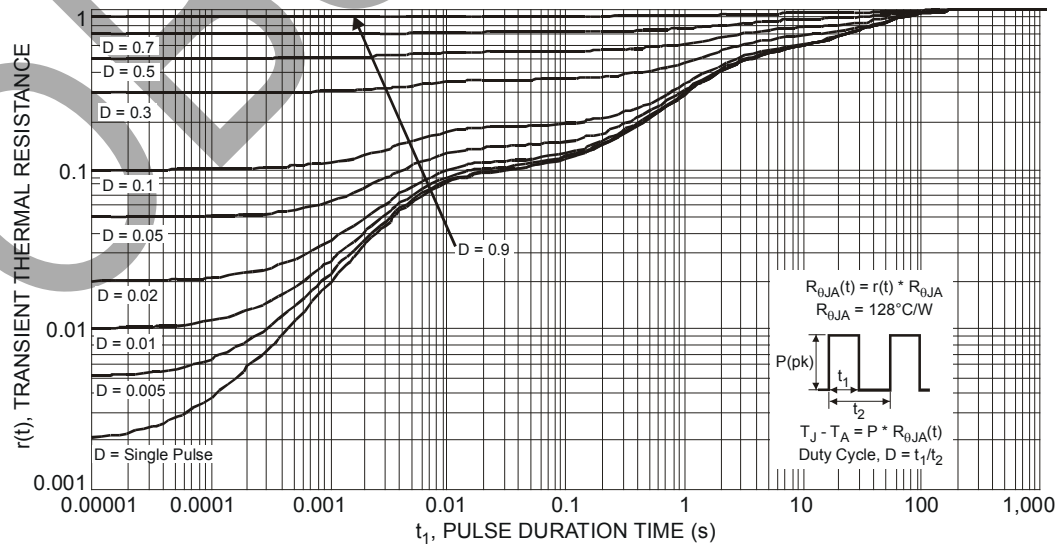


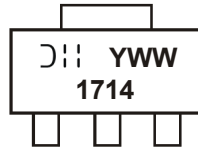
Fig. 10 Transient Thermal Response

**Ordering Information** (Note 6)

Part Number	Case	Packaging
2DB1714-13	SOT89-3L	2500/Tape & Reel

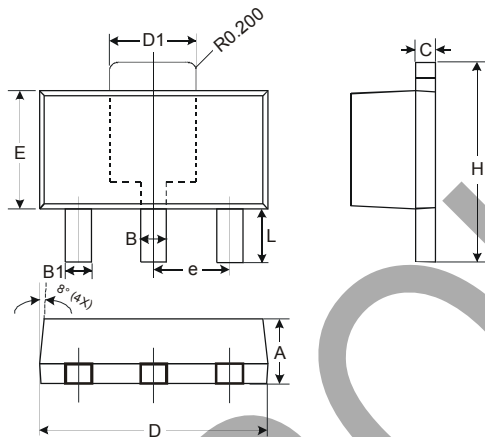
Notes: 6. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

**Marking Information**



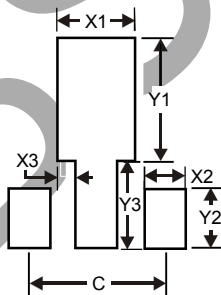
1714 = Product Type Marking Code  
 YWW = Date Code Marking  
 Y = Last digit of year (ex: 8 = 2008)  
 WW = Week code 01 - 52

**Package Outline Dimensions**



SOT89-3L			
Dim	Min	Max	Typ
A	1.40	1.60	1.50
B	0.45	0.55	0.50
B1	0.37	0.47	0.42
C	0.35	0.43	0.38
D	4.40	4.60	4.50
D1	1.50	1.70	1.60
E	2.40	2.60	2.50
e	—	—	1.50
H	3.95	4.25	4.10
L	0.90	1.20	1.05
All Dimensions in mm			

**Suggested Pad Layout**



Dimensions	Value (in mm)
X1	1.7
X2	0.9
X3	0.4
Y1	2.7
Y2	1.3
Y3	1.9
C	3.0

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